

IN THE CLAIMS

1 (cancelled).

2 (Currently amended). ~~The integrated circuit structure of Claim 1~~

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A body comprising a semiconductor substrate which has a top surface and a bottom surface, wherein one or more through holes pass through the substrate between the top and bottom surfaces, the body comprising one or more circuit elements formed in and/or over the top surface of the semiconductor substrate;

a conductor formed in each through hole and protruding from the bottom surface of the semiconductor substrate, the conductor in each through hole being coupled to one or more of the circuit elements;

a dielectric separating the conductor in each through hole from the semiconductor substrate, wherein at each through hole the dielectric forms a protrusion on the bottom of the body around the conductor;

wherein at each through hole the conductor protrudes from the dielectric on the bottom of the body, the conductor thus having a protruding outer surface not covered by the dielectric, wherein at least a portion of the protruding outer surface is either vertical or sloped outwards (laterally away from the through hole) when the surface is traced down;

wherein throughout each protrusion formed by the dielectric, the dielectric becomes gradually thinner around the adjacent conductor as the protrusion is traced down.

3 (Currently amended). ~~The integrated circuit structure of Claim 1~~ in combination with a first substrate, wherein the integrated circuit structure comprises:

a body comprising a semiconductor substrate which has a top surface and a bottom surface, wherein one or more through holes pass through the substrate between the top and bottom surfaces, the body comprising one or more circuit elements formed in and/or over the top surface of the semiconductor substrate;

a conductor formed in each through hole and protruding from the bottom surface of the semiconductor substrate, the conductor in each through hole being coupled to one or more of the circuit elements;

a dielectric separating the conductor in each through hole from the semiconductor substrate, wherein at each through hole the dielectric forms a protrusion on the bottom of the body around the conductor;

wherein at each through hole the conductor protrudes from the dielectric on the bottom of the body, the conductor thus having a protruding outer surface not covered by the dielectric, wherein at least a portion of the protruding outer surface extends downward and faces laterally away from the through hole, and said portion of the protruding outer surface is either vertical or sloped outwards (laterally away from the through hole) when the surface is traced down;

wherein the protruding outer surface of each conductor is attached to the first substrate with a bonding material to form providing a conductive bond between the conductor and the first substrate, wherein the bonding material reaches and at least partially covers said portion of the protruding outer surface portion which is either vertical or sloped outwards.

4 (Currently amended). The integrated circuit structure of Claim 3 in combination with the first substrate, wherein the bonding material comprises solder which bonds the conductor to the first substrate, wherein the solder reaches and at least partially covers said portion of the protruding outer surface portion which is either vertical or sloped outwards.

5 (Original). The integrated circuit structure of Claim 3 in combination with the first substrate, wherein:

said portion of the protruding outer surface of the conductor is sloped outwards; and

the bonding material fills the entire space between the integrated circuit structure and the first substrate.

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6 (Currently amended). The integrated circuit of Claim [[1]] 3 wherein the conductor comprises a first conductive layer and a second conductive layer separating the first conductive layer from the dielectric;

wherein the second conductive layer is not present on the protruding outer surface.

7 (Original). The integrated circuit of Claim 6 wherein the first conductive layer is solder wettable, and the second conductive layer is not solder wettable.

8 (Currently amended). An integrated circuit structure comprising:

a body comprising a semiconductor substrate which has a first surface and a second surface, wherein one or more through holes pass through the substrate between the first and second surfaces, the body comprising one or more circuit elements formed in and/or over the first surface of the semiconductor substrate;

a conductor formed in each through hole and protruding from the a bottom surface of the semiconductor substrate, the conductor in each through hole being coupled to one or more of the circuit elements;

a dielectric separating the conductor in each through hole from the semiconductor substrate, wherein at each through hole the dielectric forms a protrusion on the bottom surface of the body around the conductor;

wherein throughout each protrusion formed by the dielectric, the dielectric becomes gradually thinner around the adjacent conductor as the protrusion is traced down.

9 (Currently amended). The integrated circuit structure of Claim 8 wherein at each through hole the conductor protrudes from the dielectric on the bottom surface of the body.

10 (Currently amended). The integrated circuit structure of Claim 8 in combination with a first substrate, wherein ~~the~~ a protruding portion of each protruding conductor is attached to the first substrate.

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Claims 11-27 (canceled).

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